



## Material Content Data Sheet



<b>Sales Product Name</b>				IPD30N06S4L-23		<b>Issued</b>		25. January 2018	
<b>MA#</b>				MA001042362					
<b>Package</b>				PG-TO252-3-11		<b>Weight*</b>		389.84 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.858	0.22	0.22	2200	2200	
leadframe	non noble metal	iron	7439-89-6	0.140	0.04		359		
	inorganic material	phosphorus	7723-14-0	0.042	0.01		108		
	non noble metal	copper	7440-50-8	139.706	35.83	35.88	358368	358835	
wire	non noble metal	aluminium	7429-90-5	0.913	0.23	0.23	2343	2343	
encapsulation	organic material	carbon black	1333-86-4	1.485	0.38		3809		
	plastics	epoxy resin	-	25.983	6.67		66652		
	inorganic material	silicondioxide	60676-86-0	121.009	31.04	38.09	310407	380868	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9594	9594	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		233		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	234	
solder	noble metal	silver	7440-22-4	0.031	0.01		81		
	non noble metal	tin	7440-31-5	0.025	0.01		65		
	non noble metal	lead	7439-92-1	1.203	0.31	0.33	3086	3232	
heatspreader	inorganic material	phosphorus	7723-14-0	0.028	0.01		73		
	non noble metal	iron	7439-89-6	0.095	0.02		243		
	non noble metal	copper	7440-50-8	94.488	24.24	24.27	242378	242694	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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